

Action Map – Scrap Reduction Challenge eLearning

I collaborated with technical trainers and senior human resource leaders as the SME's and primary stakeholder decision makers. Together, we created the action map below in response to the problem of excess scrap being created by production technicians in the semiconductor fab. The problem results in wasted time and cost. SME's identified two primary actions needed to remedy the excess scrap problem: following proper gowning procedures and proper handling of wafers. These actions specify the following business goal: *By 7/1/25, all production technicians (aka techs) working in the semiconductor fab will decrease scrap by 15% in their respective functional area by following proper gowning and wafer handling procedures.* Each action is linked to specific behaviors production technicians need to follow in order to accomplish the goal. The map below supports a Level 2 eLearning course as one appropriate intervention designed to help accomplish the business goal, as it will provide technicians with the knowledge needed to perform well on the job. After successful completion of the eLearning course with 77% accuracy, technicians will participate in an on-the-job behavioral intervention, led by a technical training mentor, where they will practice the proper gowning and wafer handling procedures learned in the self-paced eLearning course.

